2042162-1 ACTIVE

Z-PACK | Z-PACK Slim UHD

TE Internal #: 2042162-1

96 Position, Mating Alignment, Polarization Mating Alignment

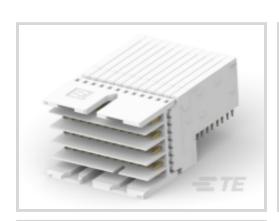
Type, 8 Row, 12 Column, Z-PACK Slim UHD, High Speed Backplane

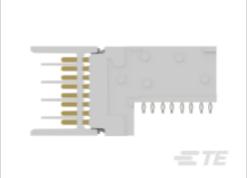
Connectors

View on TE.com >



Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Number of Positions: 96

Row-to-Row Spacing: 1.25 mm [.05 in]

Mating Alignment: With

Mating Alignment Type: Polarization

Number of Rows: 8

Features

Product Type Features

| Backplane Module Type | Center |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type | PCB Mount Header |
| Shroud Style | Unshrouded |
| Configuration Features | |
| Pairs per Column | 8 |
| Number of Pairs | 48 |
| Stackable | Yes |
| Number of Signal Positions | 96 |
| Number of Positions | 96 |
| Number of Rows | 8 |
| Number of Columns | 12 |
| PCB Mount Orientation | Right Angle |



Electrical Characteristics

| Impedance | 30 Ω |
|-------------------|--------|
| Operating Voltage | 30 VAC |

Signal Characteristics

| Data Rate | 20 Gb/s | |
|-----------|---------|--|

Body Features

| Shield Material | Copper Alloy |
|-----------------------|--------------|
| Primary Product Color | Natural |

Contact Features

| PCB Contact Termination Area Plating Material Thickness | .5 – 2.5 μm[20 – 100 μin] |
|---|---------------------------|
| Contact Type | Pin |
| Contact Shape & Form | Dual Beam |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Copper Alloy |
| Contact Current Rating (Max) | .5 A |

Termination Features

| Termination Post & Tail Length | 1.6 mm[.493 in] |
|--------------------------------|--------------------------|
| Termination Method to PCB | Through Hole - Press-Fit |

Mechanical Attachment

| Guide Hardware | Without |
|--------------------------|-----------------------|
| Mating Retention | Without |
| PCB Mount Alignment | With |
| PCB Mount Retention | With |
| PCB Mount Retention Type | Action/Compliant Tail |
| Mating Alignment | With |
| Mating Alignment Type | Polarization |

Housing Features

| Number of Shrouded Sides | 0 |
|--------------------------|------------------------------|
| End Wall Location | None |
| Housing Material | LCP (Liquid Crystal Polymer) |
| Centerline (Pitch) | 1.45 mm[.057 in] |



Dimensions

| Connector Length | 17.3 mm[.681 in] |
|-----------------------------|----------------------------|
| Connector Height | 9.5 mm[.374 in] |
| Connector Width | 12.51 mm[.493 in] |
| PCB Thickness (Recommended) | 1.2 mm |
| PCB Hole Diameter | .4 mm[.016 in] |
| Row-to-Row Spacing | 1.25 mm[.05 in] |
| Usage Conditions | |
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
| Operation/Application | |
| Durability Rating | 200 Cycles |
| Circuit Application | Signal |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| | |

Tray

Product Compliance

Packaging Method

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Not applicable for solder process capability |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these



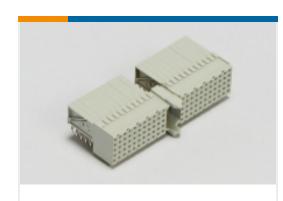
limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | Z-PACK Slim UHD







High Speed Backplane Connectors(12)

Customers Also Bought

























Documents

Product Drawings

Right Angle Male Connector

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2042162-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2042162-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2042162-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English

Agency Approvals

UL Report

English